

Lecture 9b
of
EEE201

CMOS Digital Integrated Circuits

Department of Electrical & Electronic Engineering
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Monday, 04th November 2024

□ CMOS IC Layout Design continued

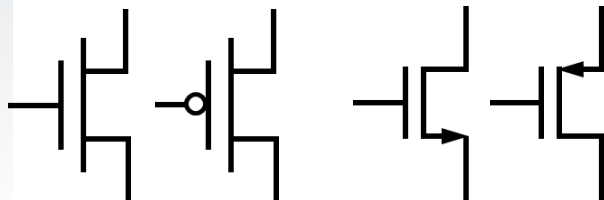
- extend from CMOS inverter foundation
- NAND & NOR logic gates
- complicated logic gates



CMOS Inverter as Foundation

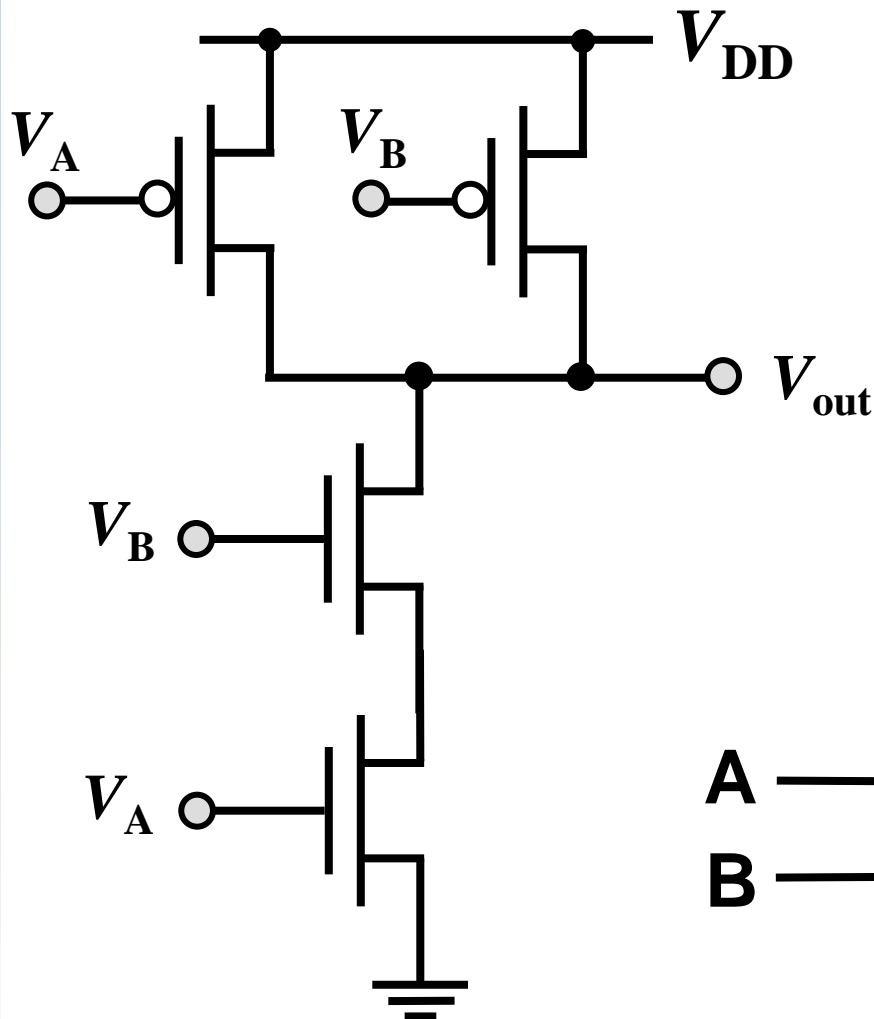
(principles extending to NAND, NOR & other logic gates)

- ❑ With the foundation of CMOS inverter's operation and design, the principles can be extended to the NAND gate, the NOR gate and complicated logic gates.
 - logic “0” represented by a low voltage, typically 0 V
 - logic “1” represented by a high voltage, typically V_{DD}
 - nMOSFETs & pMOSFETs in **complementary** circuit operation
 - assumed proper connection of the body terminals of the MOSFETs if not shown in the circuit symbols:



NAND Logic - CMOS implementation

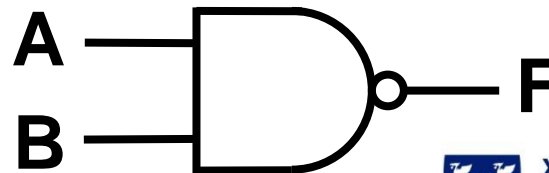
(2 nMOSFETs in series & 2 pMOSFETs in parallel)



V_A	V_B	V_{out}
0 V	0 V	V_{DD}
0 V	V_{DD}	V_{DD}
V_{DD}	0 V	V_{DD}
V_{DD}	V_{DD}	0 V



$$F = \overline{A \cdot B}$$



A	B	F
0	0	1
0	1	1
1	0	1
1	1	0

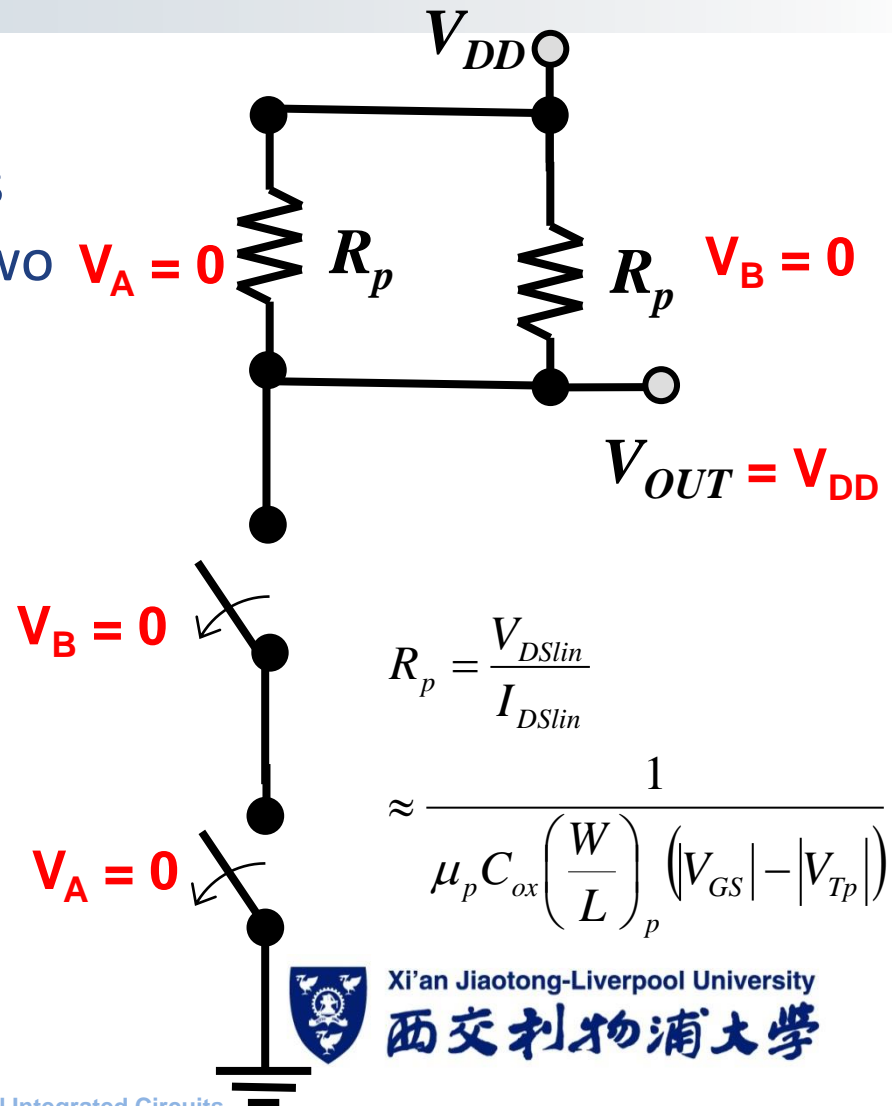
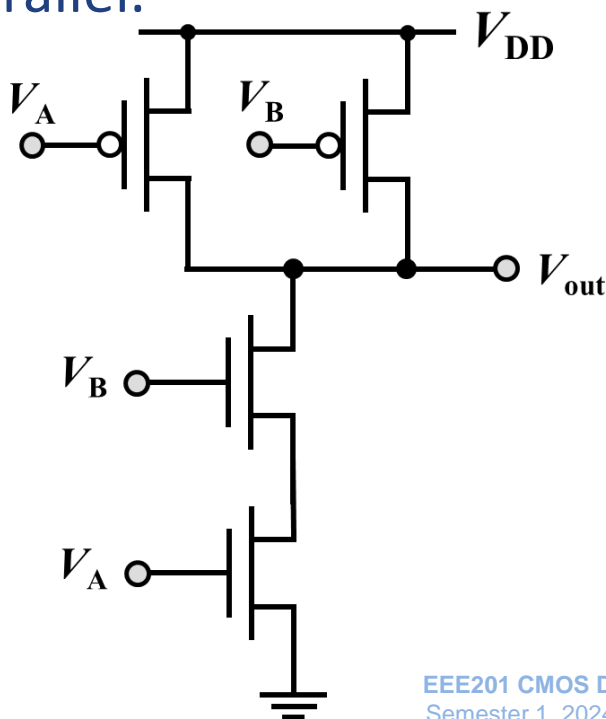


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CMOS NAND Logic Gate

(switch model of the MOSFETs – both logic “0” at inputs)

- When both inputs are logic “0” (i.e. $V_A = V_B = 0$ V), V_{out} is connected to V_{DD} through two equivalent resistances R_p in parallel.

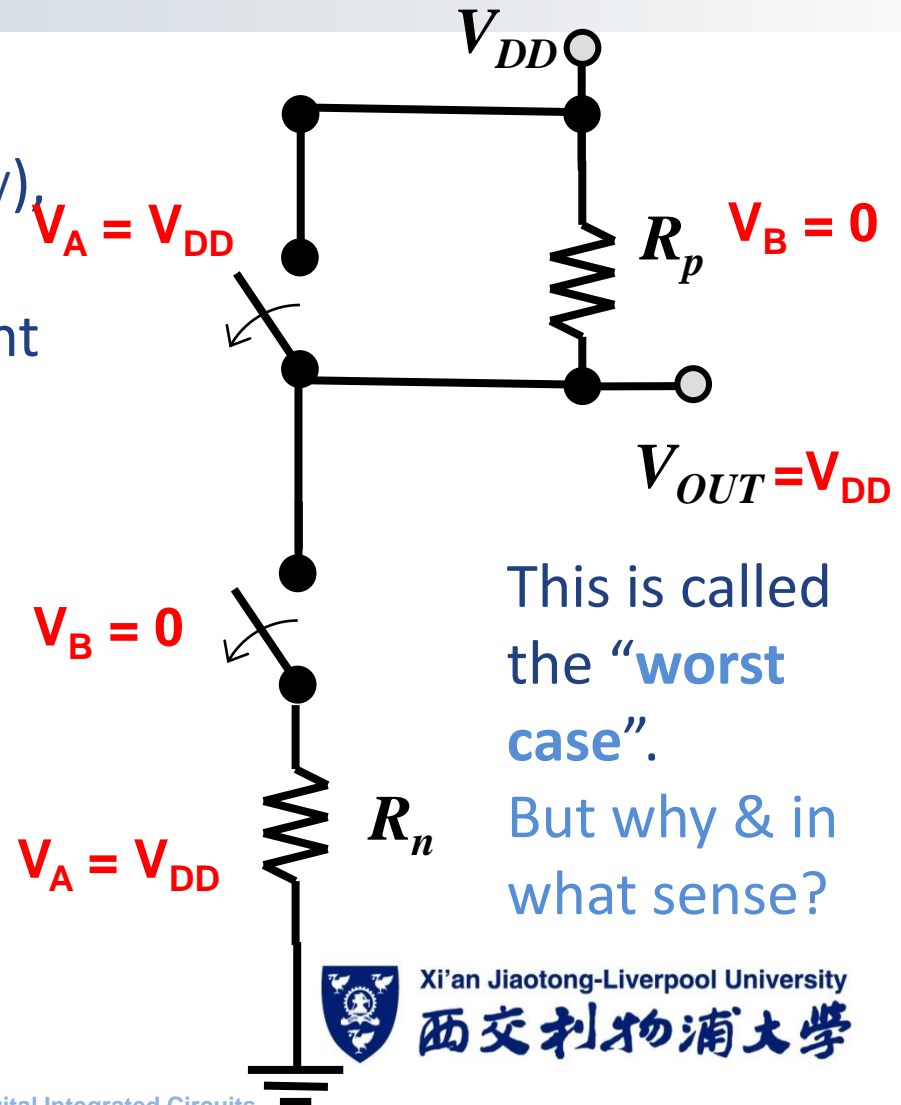
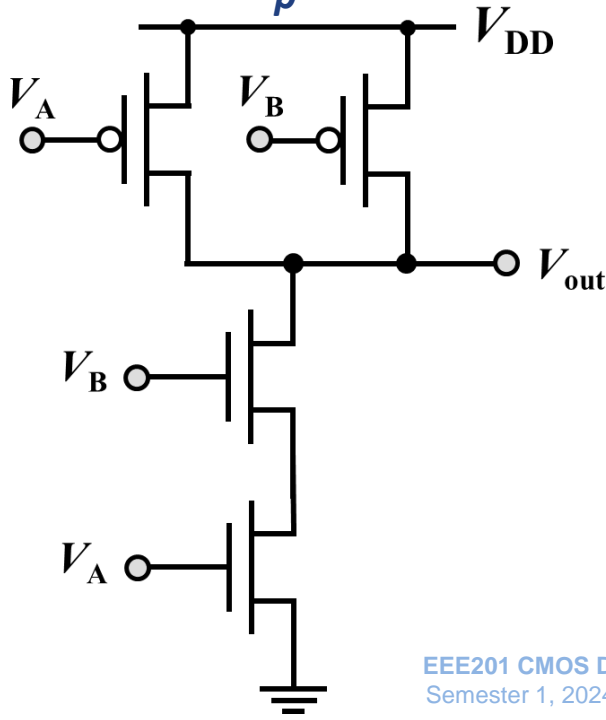


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CMOS NAND Logic Gate

(different inputs)

- When the two inputs are different (e.g. $V_A = V_{DD}$ & $V_B = 0$ V), V_{out} is connected to V_{DD} through only one equivalent resistances R_p .



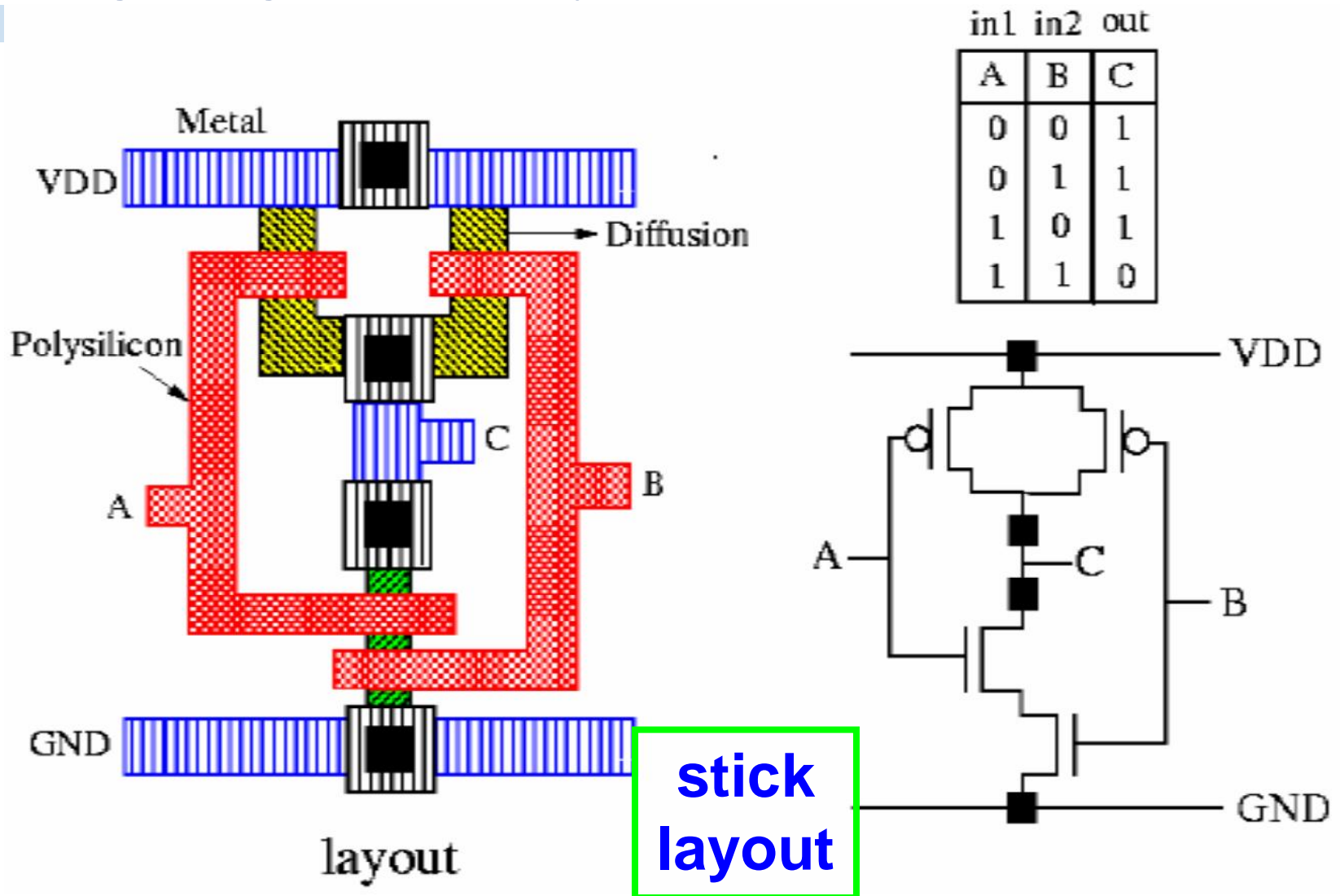
This is called the “**worst case**”.
But why & in what sense?



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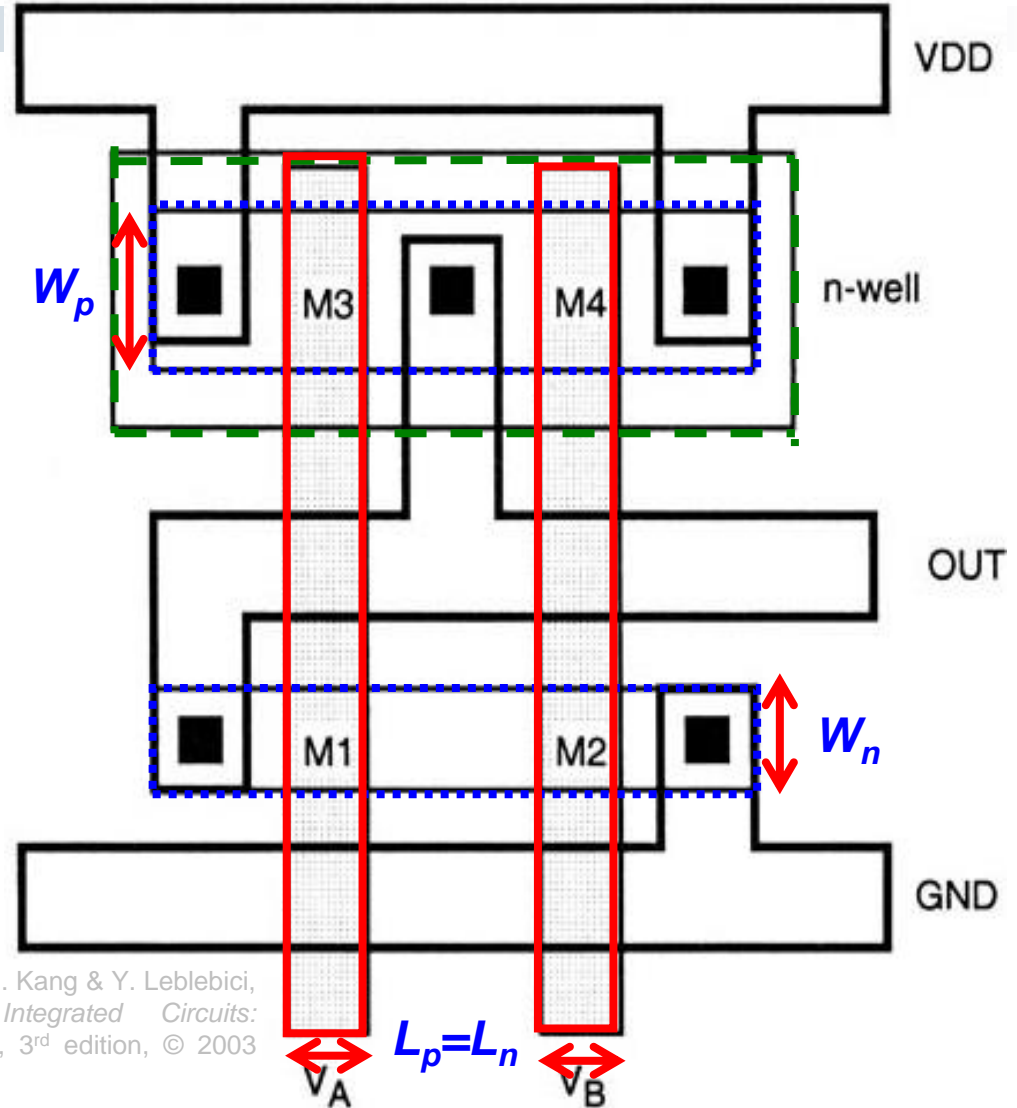
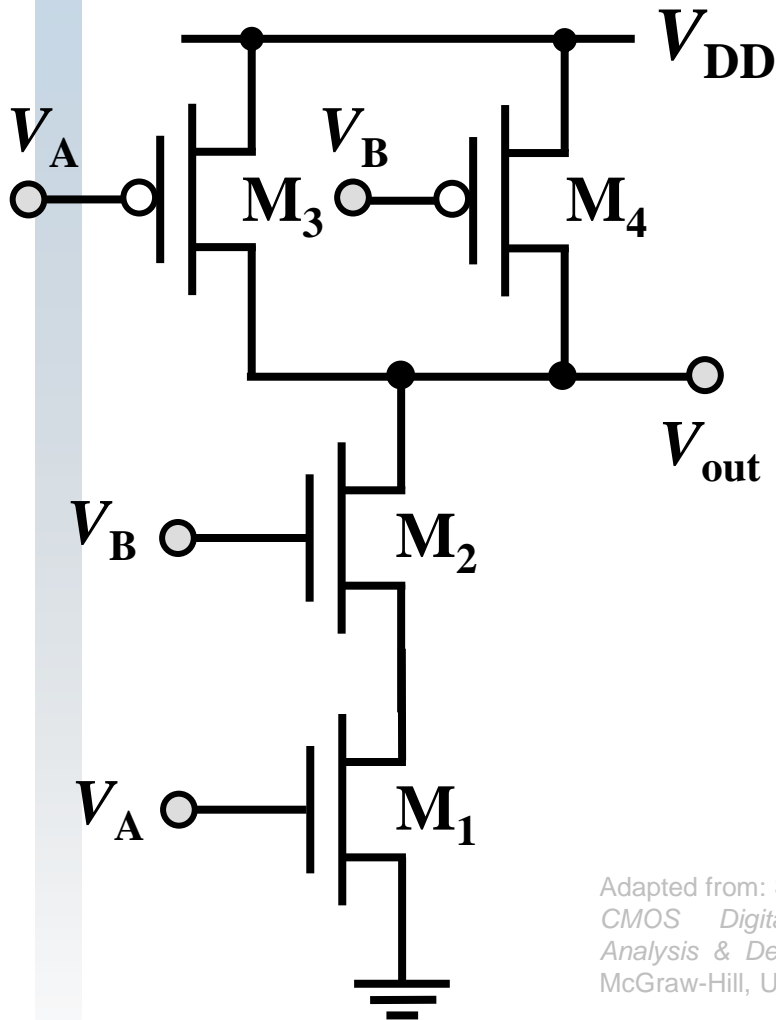
CMOS NAND Logic Gate

(rough design with stick layout)



CMOS NAND Logic Gate

(proper IC layout improved from stick layout)



Adapted from: S.-M. Kang & Y. Leblebici,
*CMOS Digital Integrated Circuits:
Analysis & Design*, 3rd edition, © 2003
McGraw-Hill, USA.

CMOS NAND Logic Gate

(MOSFETs' geometry in layout design)

❑ In drawing the layout of the CMOS NAND gate, there are **design considerations** in the MOSFETs' geometry:

➤ typically $L_n = L_p$ (do you know why?)

➤ usually $V_{TOn} = |V_{TOp}|$ in CMOS logic technology

➤ $I_{Dn} = |I_{Dp}|$ (or equivalently $R_{neq} = R_{peq}$) for the same fall time and rise time at the output

➤ if inputs are different (i.e. $V_A \neq V_B$), then $\mu_n \left(\frac{W_n}{2L} \right) = \mu_p \left(\frac{W_p}{L} \right)$

➤ if inputs are the same (i.e. $V_A = V_B$), then $\mu_n \left(\frac{W_n}{2L} \right) = \mu_p \left(\frac{2W_p}{L} \right)$

➤ What W_n (then W_p) to choose? \Rightarrow designer's decision

➤ Consider minimum W_p ($= 4\lambda$?), chip area, speed, power, etc.



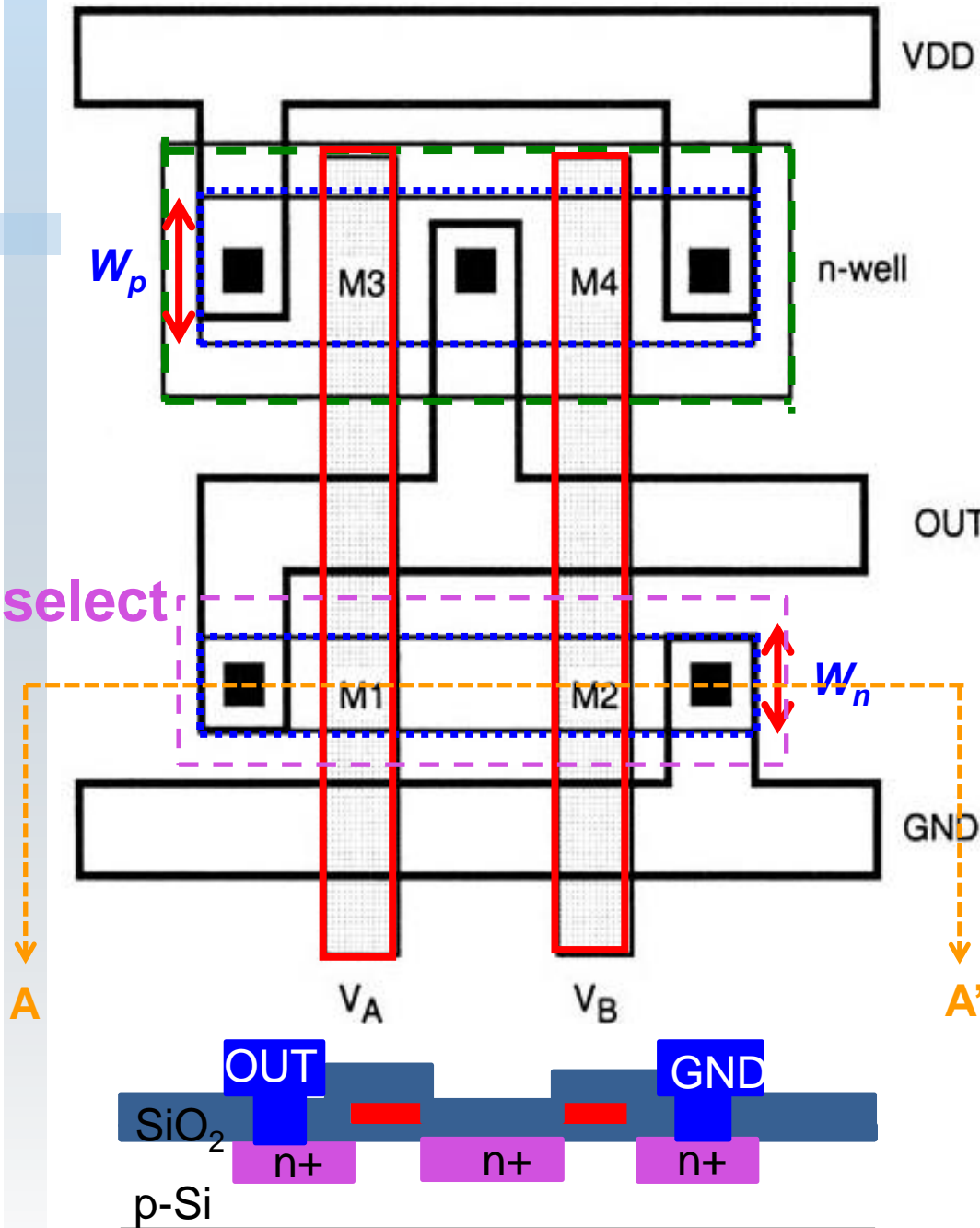
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CMOS NAND2

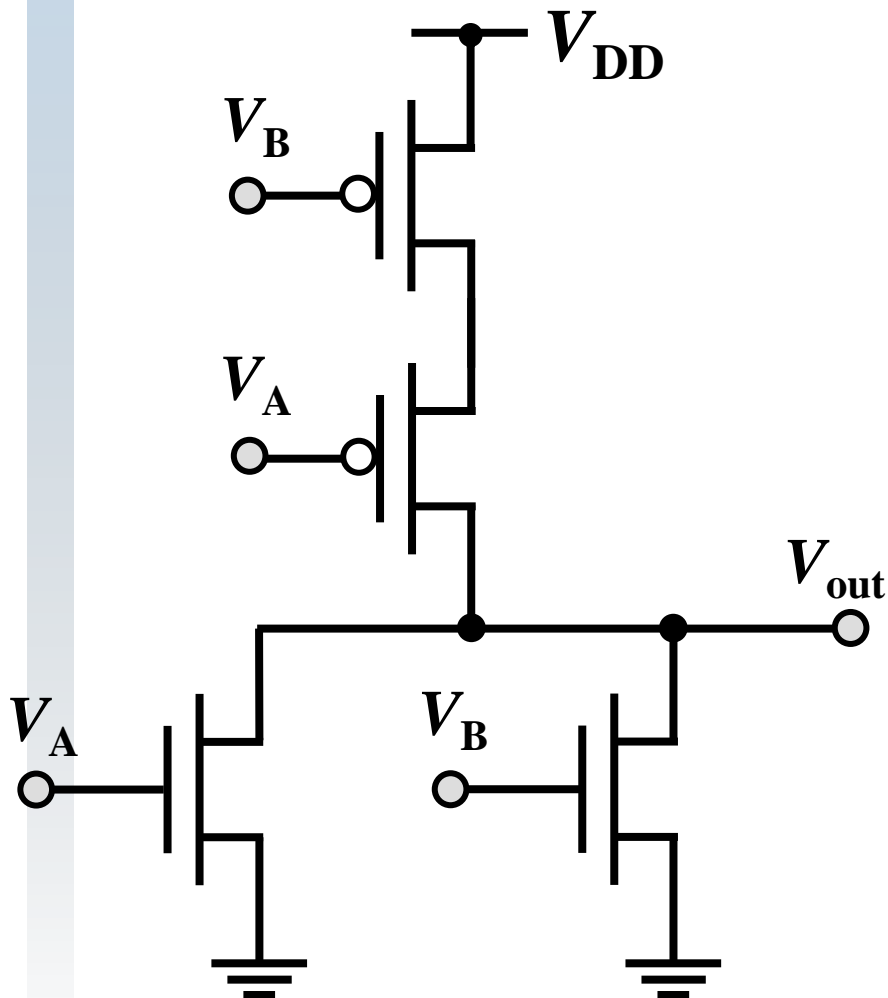
(cross-sectional structure)

- The IC layout determines what device structure will be resulted from the IC fabrication:
- Can you *visualise* (and sketch) the cross-sectional structure along the line segment AA' in the layout?



NOR Logic - CMOS implementation

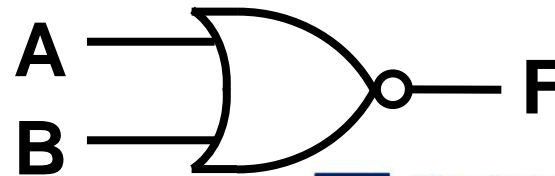
(2 nMOSFETs in parallel & 2 pMOSFETs in series)



V_A	V_B	V_{out}
0 V	0 V	V_{DD}
0 V	V_{DD}	0 V
V_{DD}	0 V	0 V
V_{DD}	V_{DD}	0 V



$$F = \overline{A + B}$$



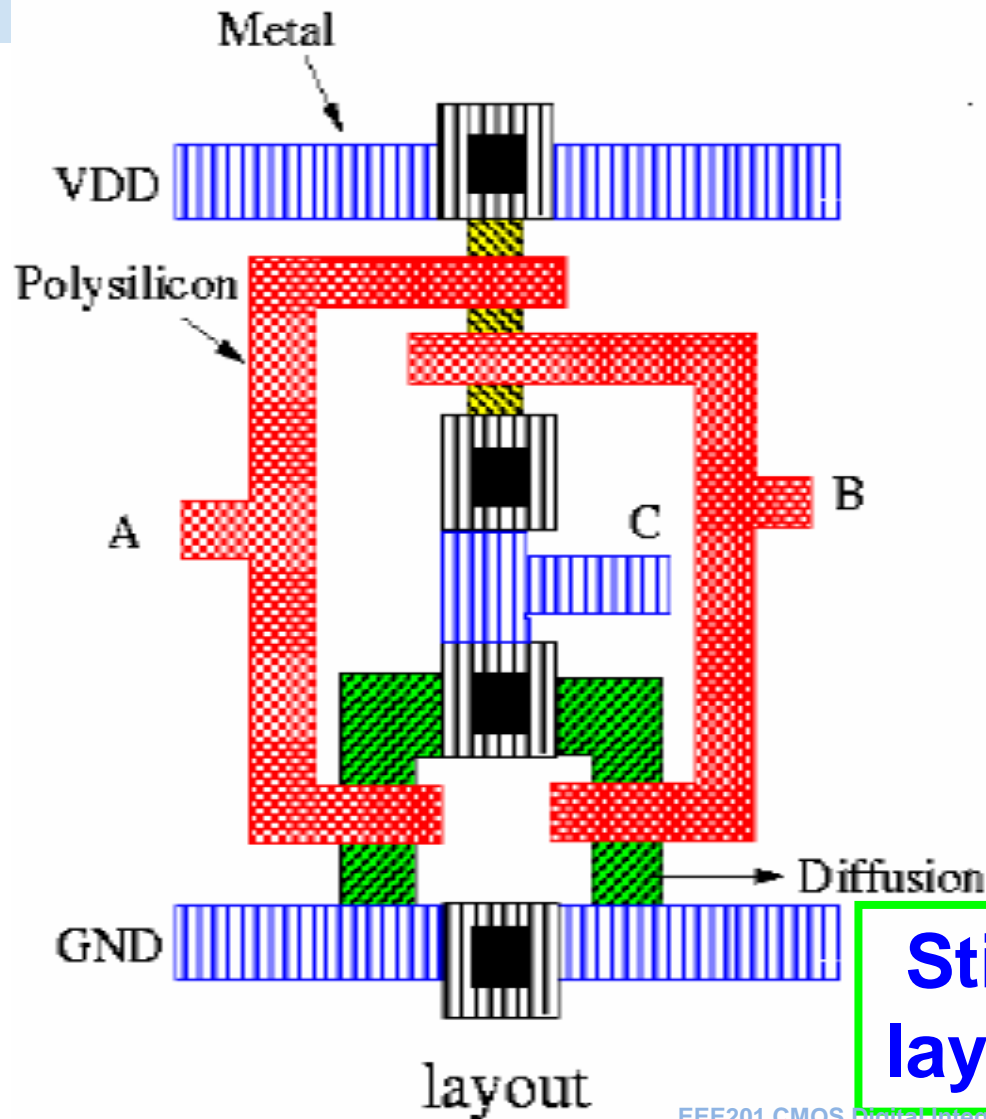
A	B	F
0	0	1
0	1	0
1	0	0
1	1	0



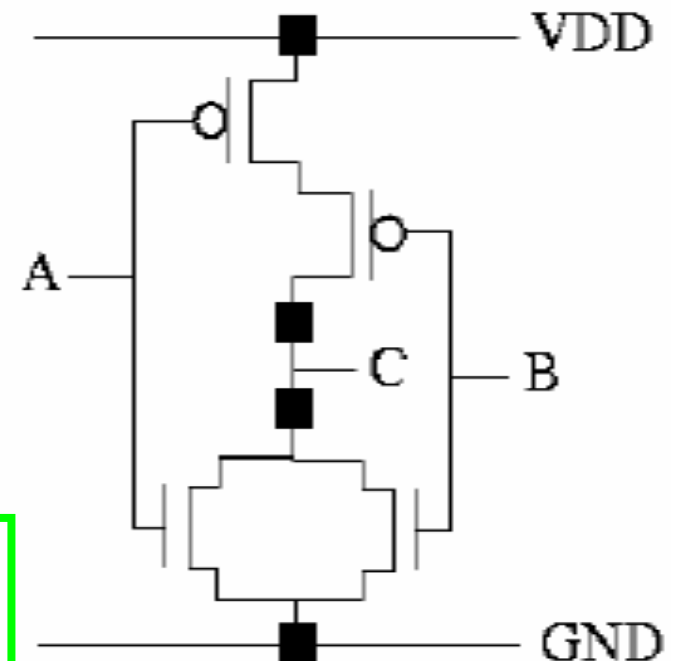
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CMOS NOR Logic Gate

(rough design with stick layout)



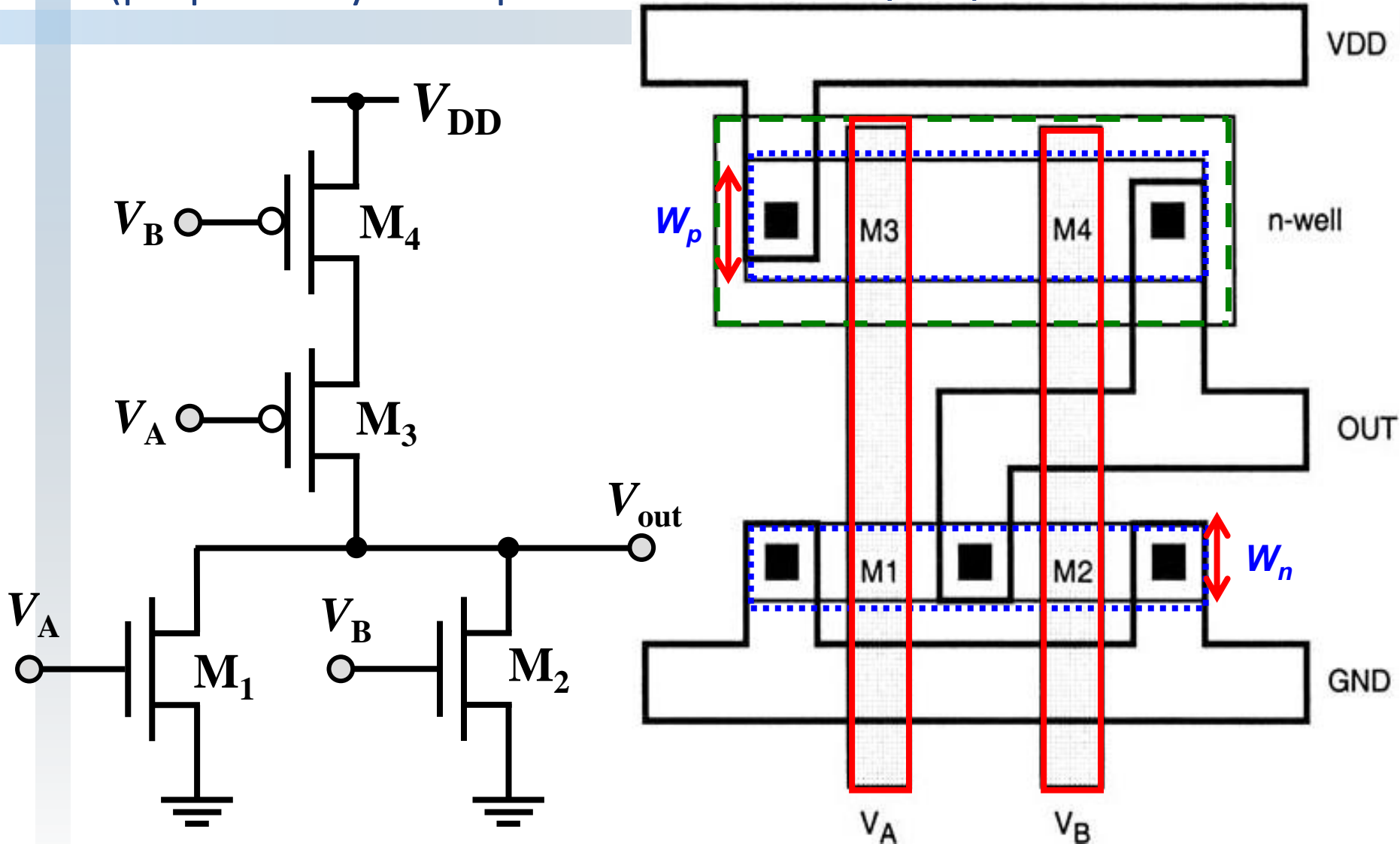
A	B	C
0	0	1
0	1	0
1	0	0
1	1	0



**Stick
layout**

CMOS NOR Logic Gate

(proper IC layout improved from stick layout)



CMOS NOR2 – design considerations

(what W_p to choose in the layout)

- ❑ In drawing the CMOS NOR gate layout, there are similar **design considerations** like those in the NAND2:
 - normally $L_n = L_p$ ($= 2\lambda$ as the minimum feature size)
 - usually $V_{TOn} = |V_{TOp}|$ in CMOS logic technology
 - $I_{Dn} = |I_{Dp}|$ (or equivalently $R_{neq} = R_{peq}$) for the same **fall time** and **rise time** at the output
 - if inputs are the same (i.e. $V_A = V_B$), then $\mu_n \left(\frac{2W_n}{L} \right) = \mu_p \left(\frac{W_p}{2L} \right)$
 - if inputs are different (i.e. $V_A \neq V_B$), then $\mu_n \left(\frac{W_n}{L} \right) = \mu_p \left(\frac{W_p}{2L} \right)$
 - Choose $W_p = 8W_n$ or $W_p = 4W_n$ (when $\mu_n = 2\mu_p$)?
 - Consider minimum W_n ($= 4\lambda$?), chip area, speed, power, etc.

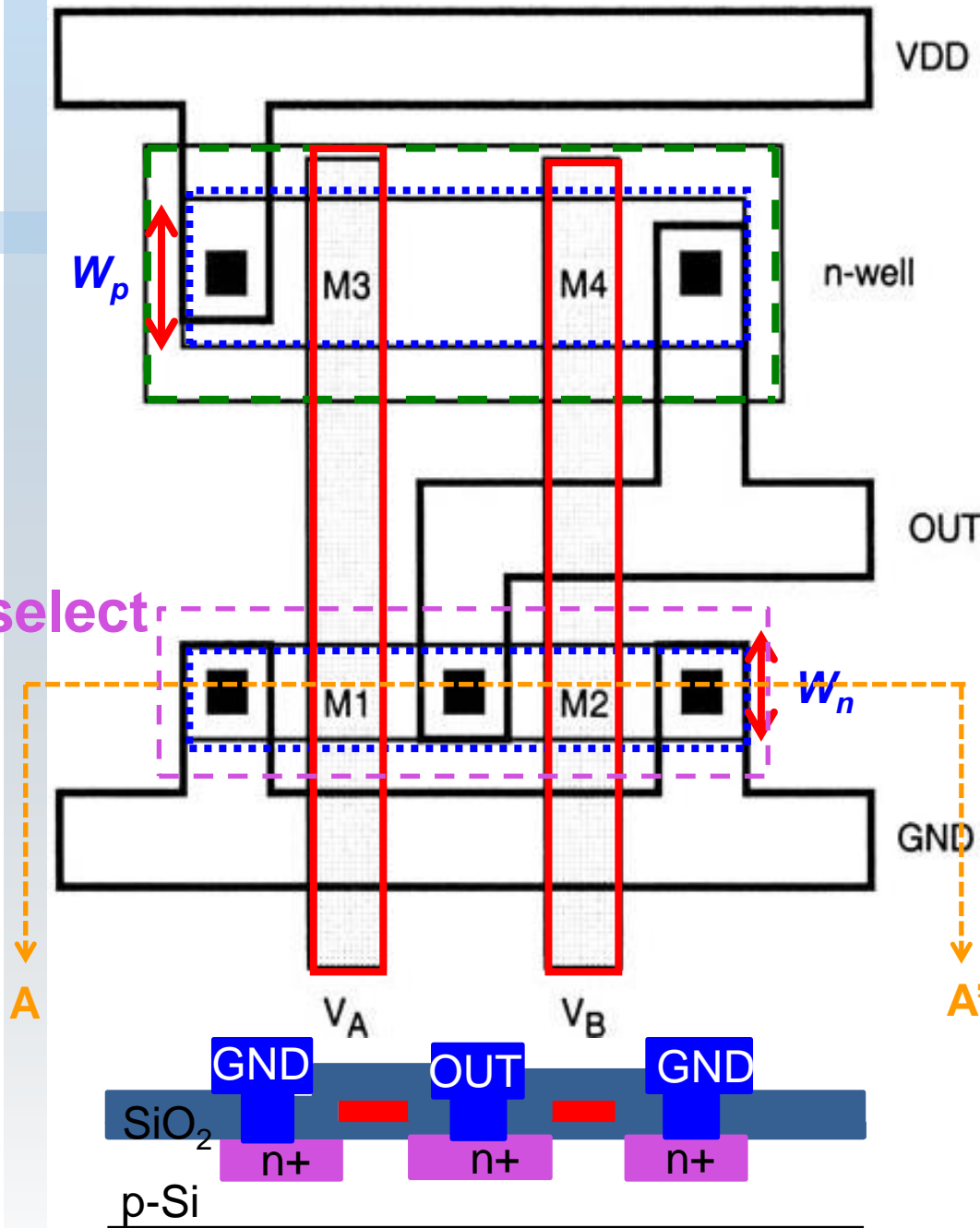


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CMOS NOR2

(cross-sectional structure)

n-select




□ The CMOS NOR gate layout looks similar to that of the NAND counterpart:

➤ Can you *visualise* (and sketch) the slightly different cross-sectional structure along the line segment AA' in the layout?


More Rules

(*n*-well & *n*-select)

- In a CMOS process, the *n*-well usually has a much lower doping concentration compared with the source/drain regions of the nMOSFETs defined by the *n*-select.

N-Well		
	1.1	Min. width
	1.2	Min. spacing (diff. potential)
	1.3	Min. spacing (same potential)


10 λ
9 λ
6 λ

Active		
	2.1	Min. width
	2.2	Min. spacing
	2.3	S/D active to well edge
	2.4	Sub. C. active to well edge (*)
	2.5	Min. spac. different implant (*)

3 λ
3 λ
5 λ
3 λ
4 λ

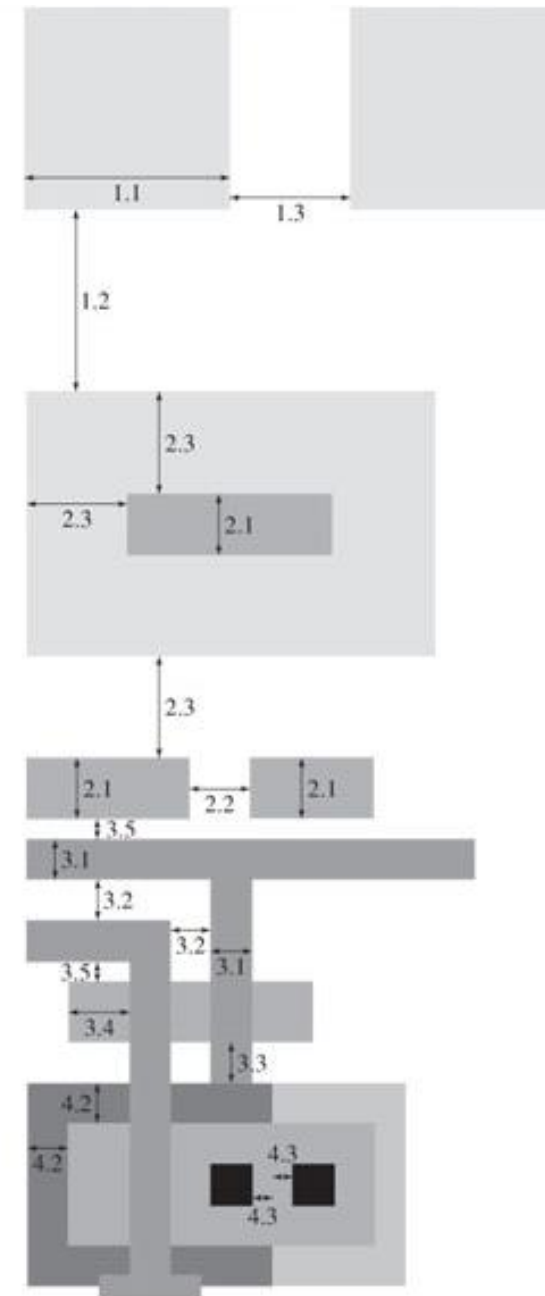
Poly		
	3.1	Min. width
	3.2	Min. spacing
	3.3	Min. gate extension
	3.4	Min. active extension to poly
	3.5	Min. field poly to active

2 λ
2 λ
2 λ
3 λ
1 λ

Select		
	4.1	Min. select spacing to gate (*)
	4.2	Min. overlap of active
	4.3	Min. overlap of contact
	4.4	Min. width and spacing (*)

3 λ
2 λ
1 λ
2 λ

(*) Not Drawn



More Ru

(via1 & metal2)

- The **via1** mask layer is similar to (with real difference from) the contact mask layer. It is the vertical electrical connection between **metal1** & **metal2**.



Contact

5.1	Exact contact size	2λ
5.2	Min. poly overlap	1.5λ
5.3	Min. spacing	2λ
5.4	Min. spacing to gate	2λ

6.1	Exact contact size	2λ
6.2	Min. active overlap	1.5λ
6.3	Min. spacing	2λ
6.4	Min. spacing to gate	2λ



Metal1

7.1	Min. width	3λ
7.2.a	Min. spacing	3λ
7.3	Min. overlap of any contact	1λ



Via1

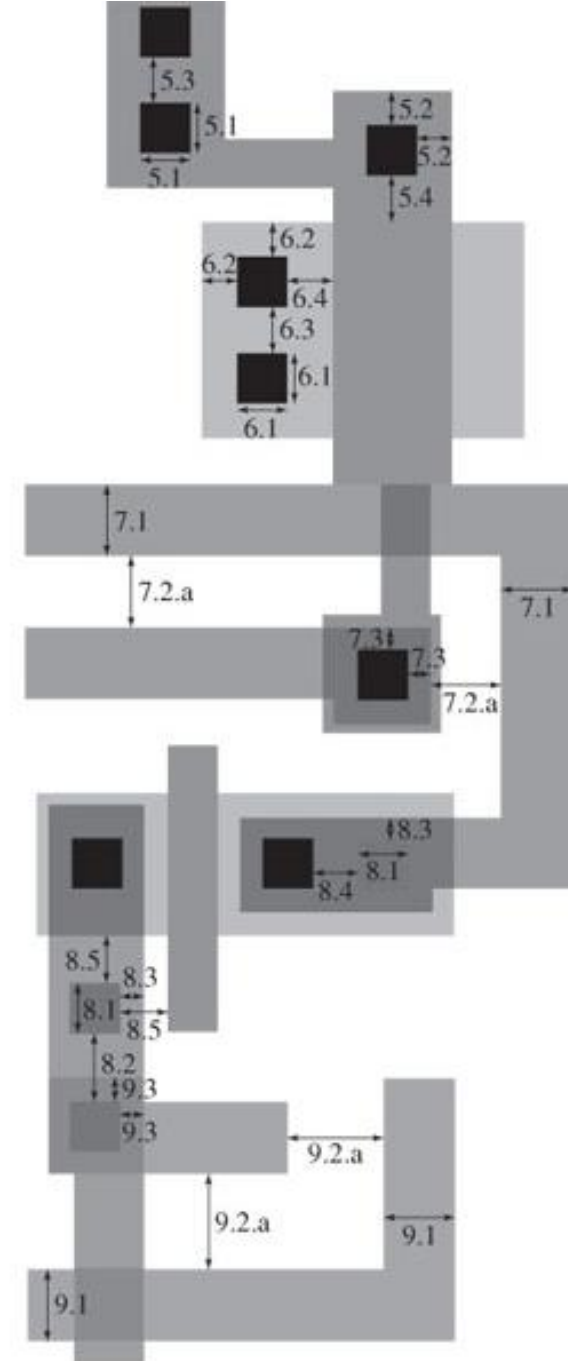
8.1	Exact size	2λ
8.2	Min. spacing	3λ
8.3	Min. overlap by metal1	1λ
8.4	Min. spacing to contact	2λ
8.5	Min. spac. to poly or act. edge	2λ



Metal2

9.1	Min. width	3λ
9.2.a	Min. spacing	4λ
9.3	Min. overlap to via1	1λ

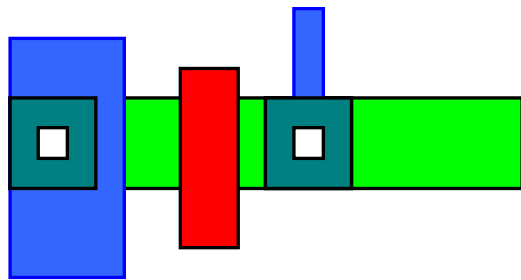
(*) Not Drawn



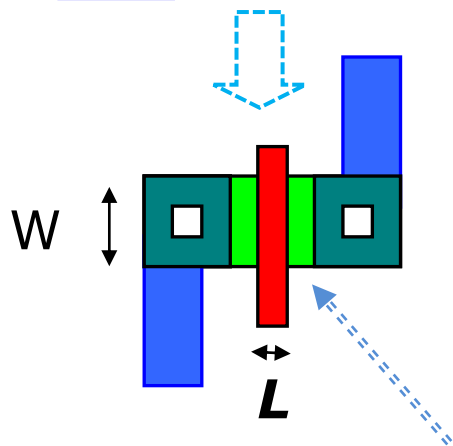
CMOS IC Layout - practical tips

(minimum channel width & other sizes in the λ -rule)

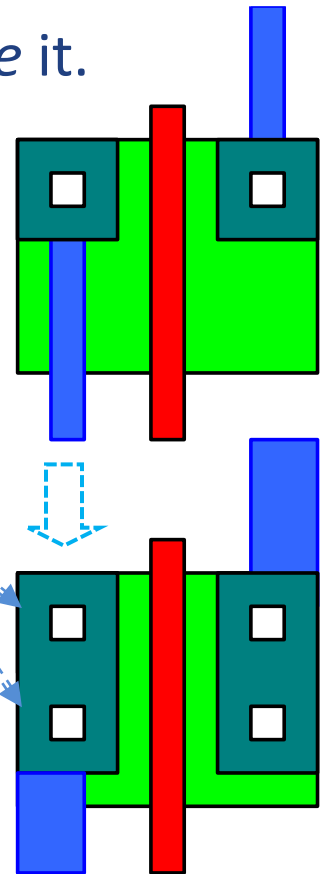
- In drawing an IC layout, it is desirable to *optimise* it.



minimum W :
 $1\lambda + 2\lambda + 1\lambda = 4\lambda$
(can it be smaller?)
minimum L : 2λ



- 1 contact allows 1 mA
- multiple contacts less series resistance



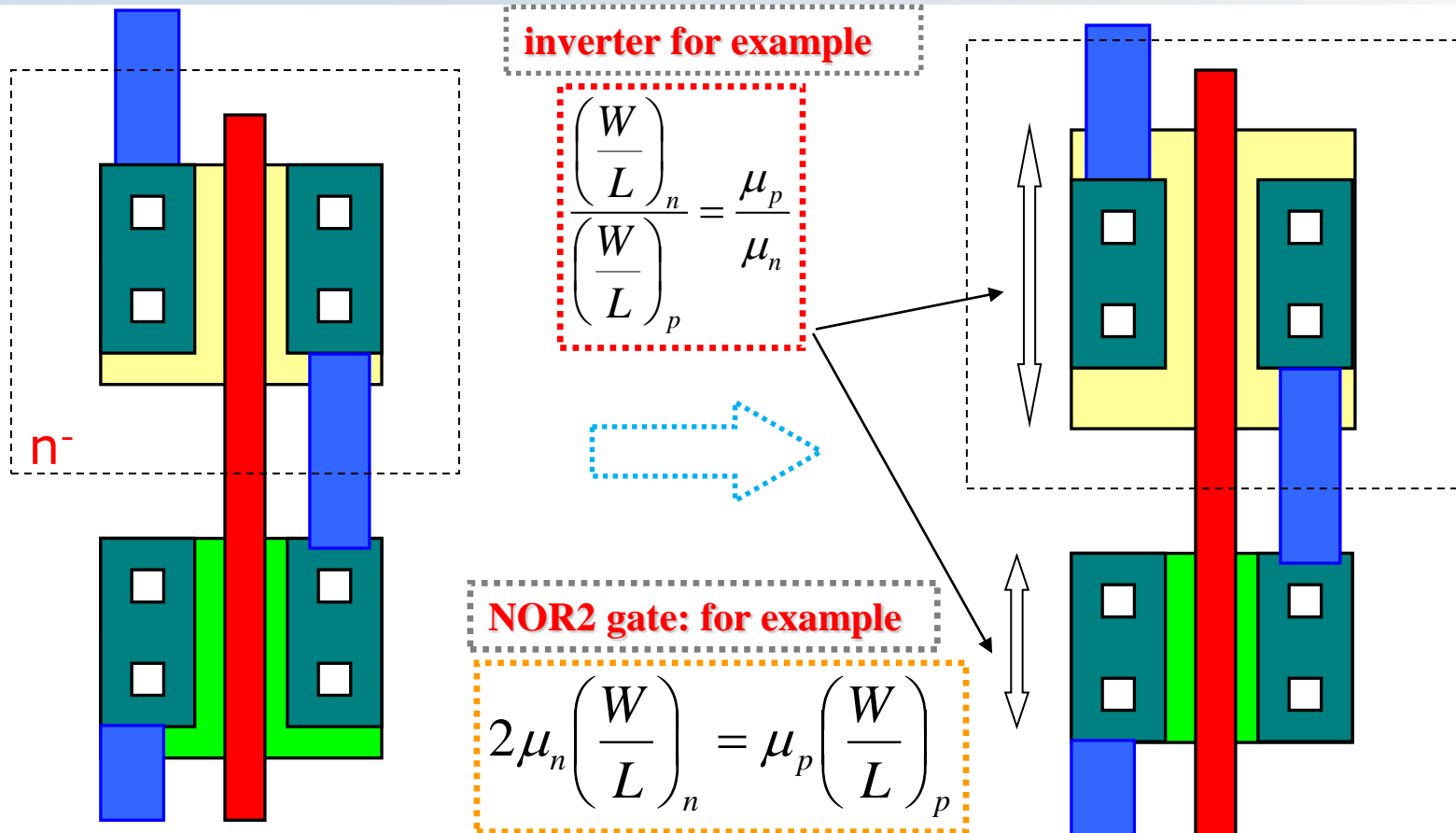
- Minimise source/drain regions
- Use minimum gate length L (2λ)



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CMOS IC Layout - practical tips

(MOSFET geometrical sizes)

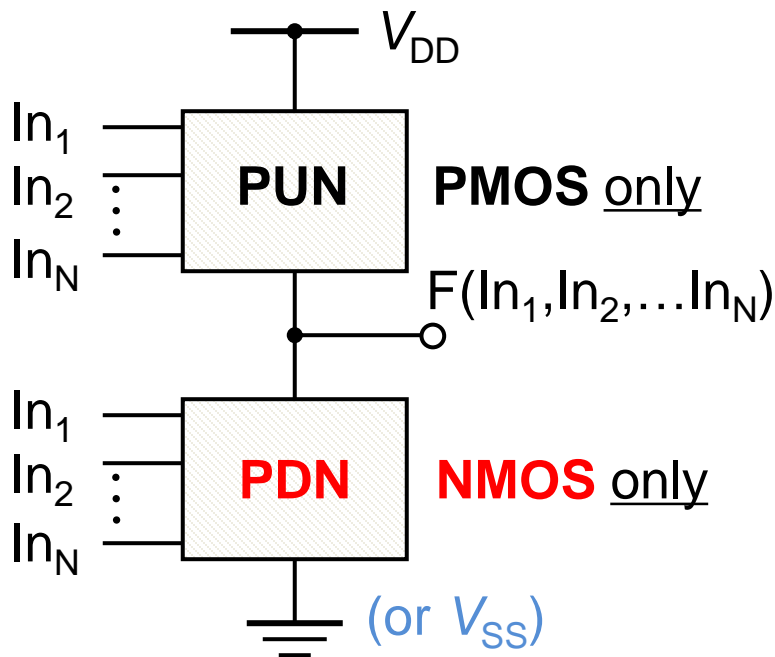


- L = minimum feature size
- $W_p = ? W_n \Rightarrow$ decision based on design consideration

From Inverter, NAND & NOR

(generalisation to CMOS logic circuits)

- ❑ Based on the CMOS logic inverter, NAND and NOR gates, the operation and design principles can be generalised to CMOS combinational logic circuits with N inputs.

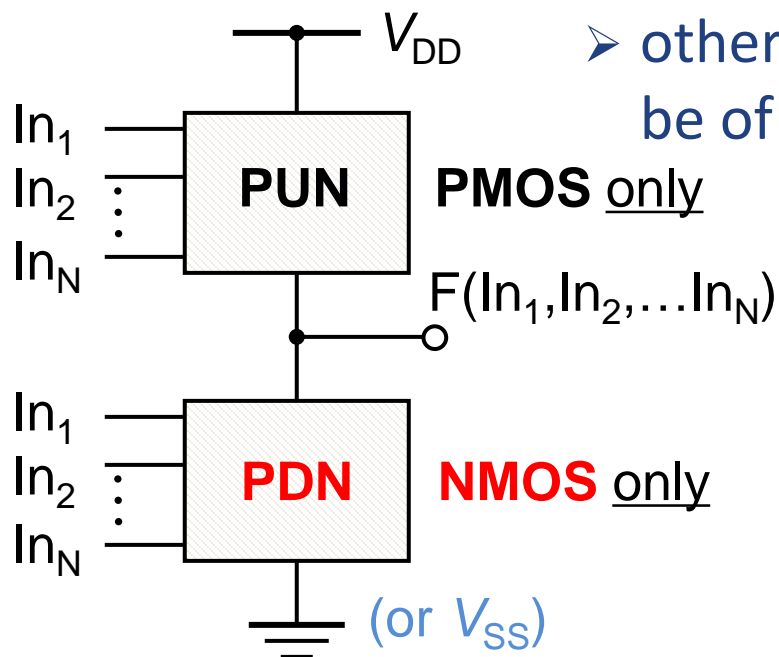


- for any combinations of inputs to produce a logic "1" at the output, the upper network of pMOSFETs should provide a low resistance path from the output to V_{DD} ;
- otherwise, the PMOS network should be of a high resistance.

CMOS Logic Circuits

(low DC power consumption)

- for any combinations of inputs to produce a logic “0” at the output, the bottom network of nMOSFETs should provide a low resistance path from the output to ground;



- otherwise, the NMOS network should be of a high resistance.

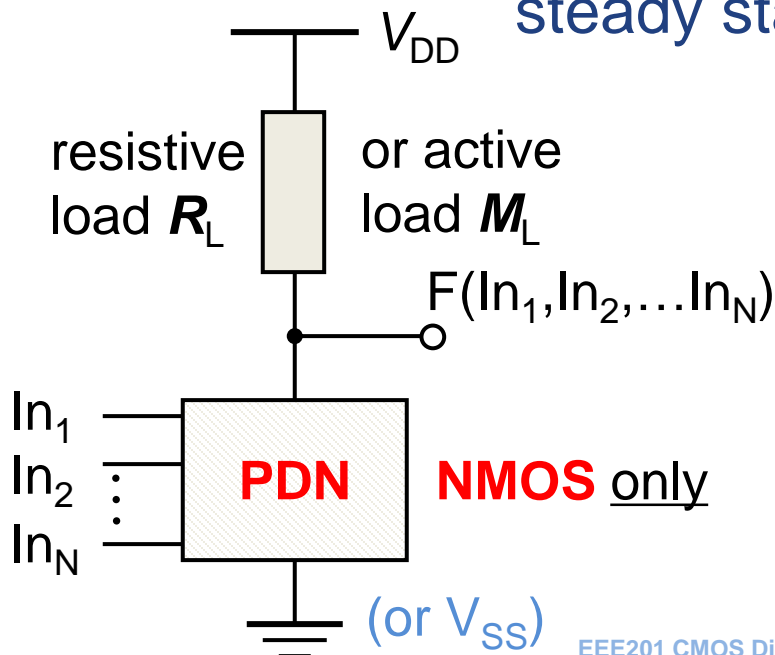
- ❑ When the output is constant, either logic “0” or “1”, the CMOS logic circuits *ideally* draws no current; (it does draw currents when the output *switches* from logic “0” to “1” or “1” to “0”).

⇒ low DC power consumption in CMOS logic

Logic Circuits with NMOS only

(generalisation to CMOS logic circuits)

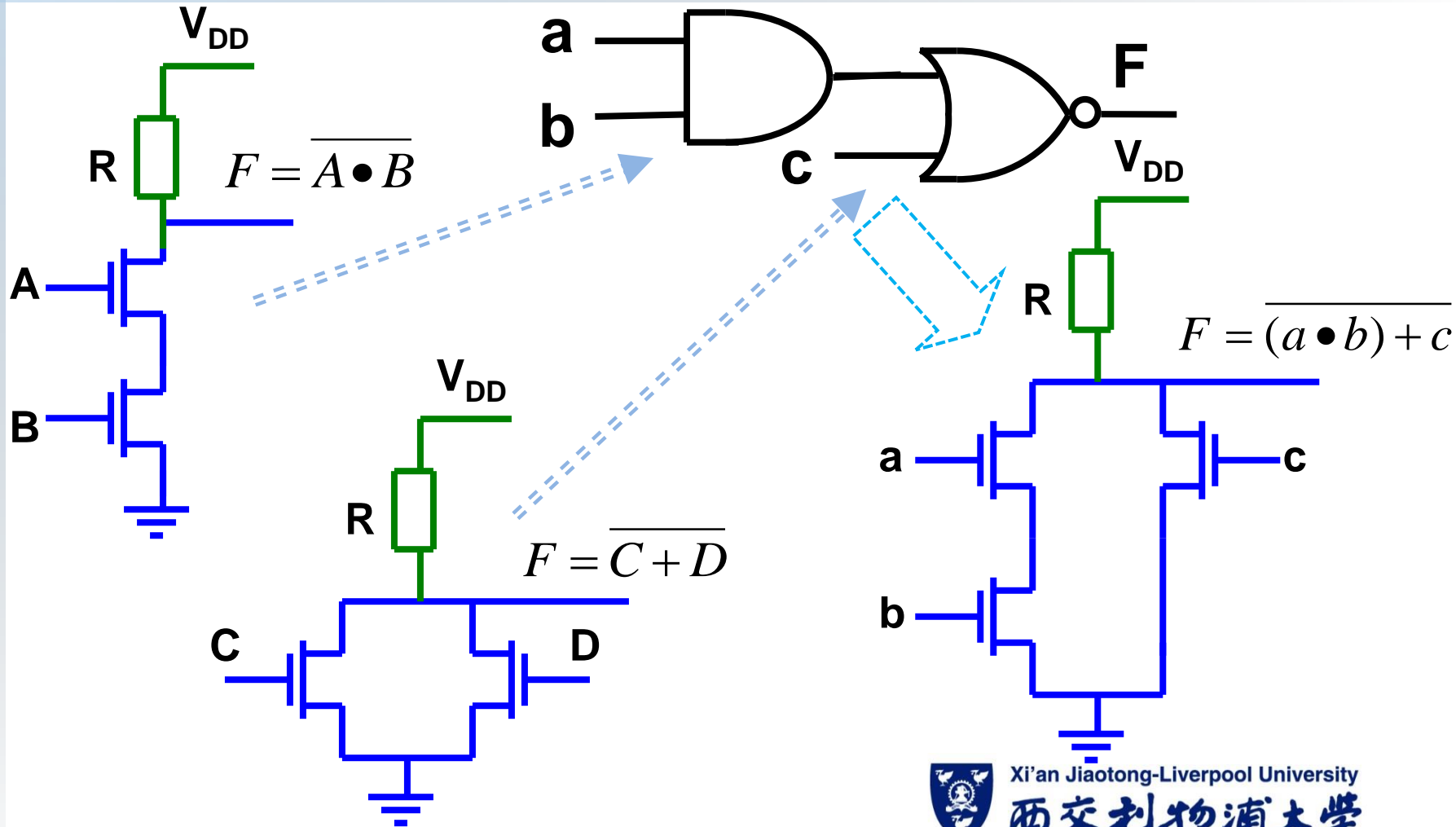
- ❑ Even without using the PMOS network but a resistive load, the circuits still work (i.e. performing the Boolean logic function).
 - However, DC power consumption is high even in the steady state (i.e. the output is constant).



- Do you know what output logic state here will draw currents steadily?
- Can we replace the NMOS network instead with a resistive load? Why or why not?

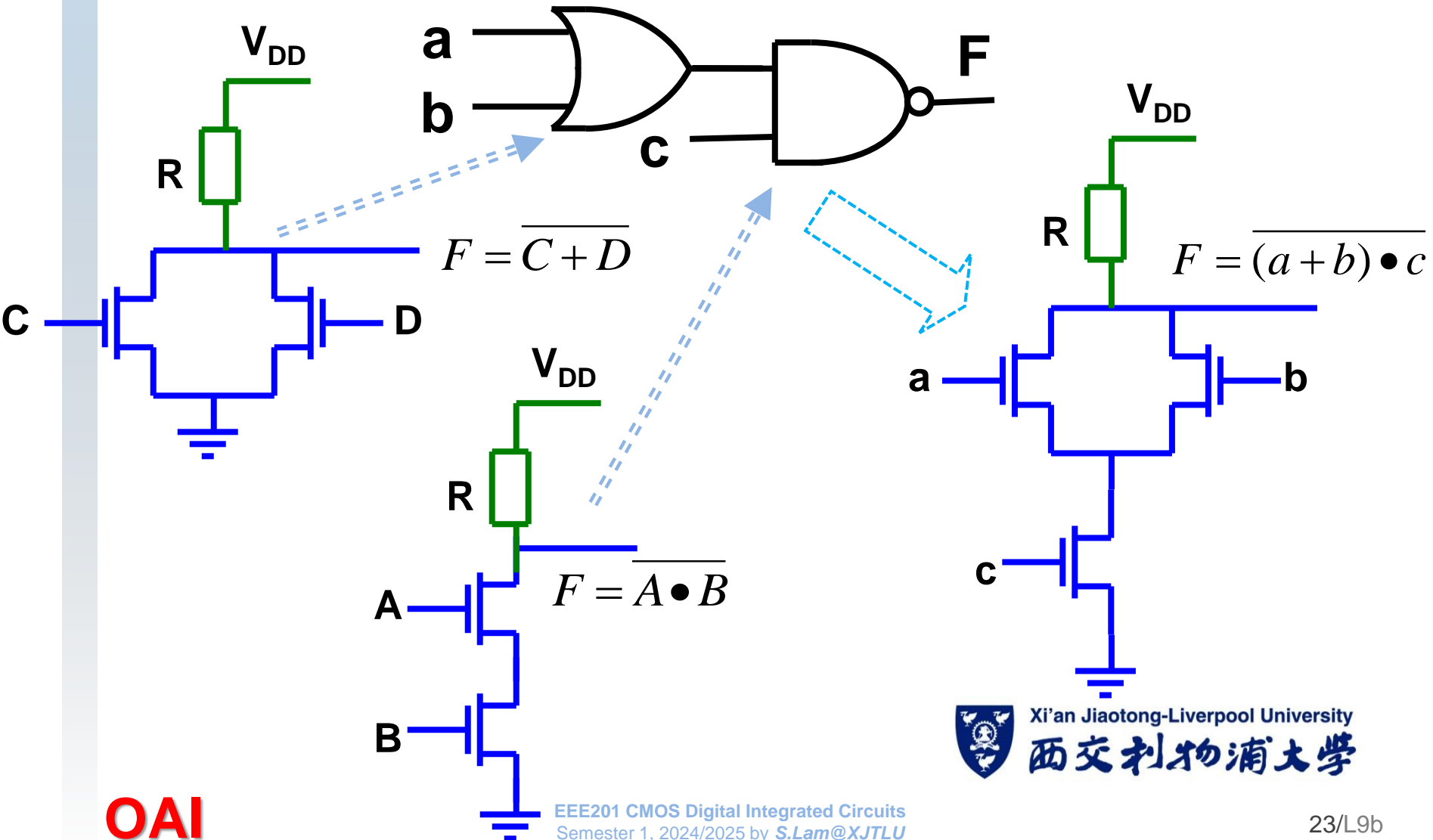
More Complicated Logic Gates

(AND-OR-Inverter)



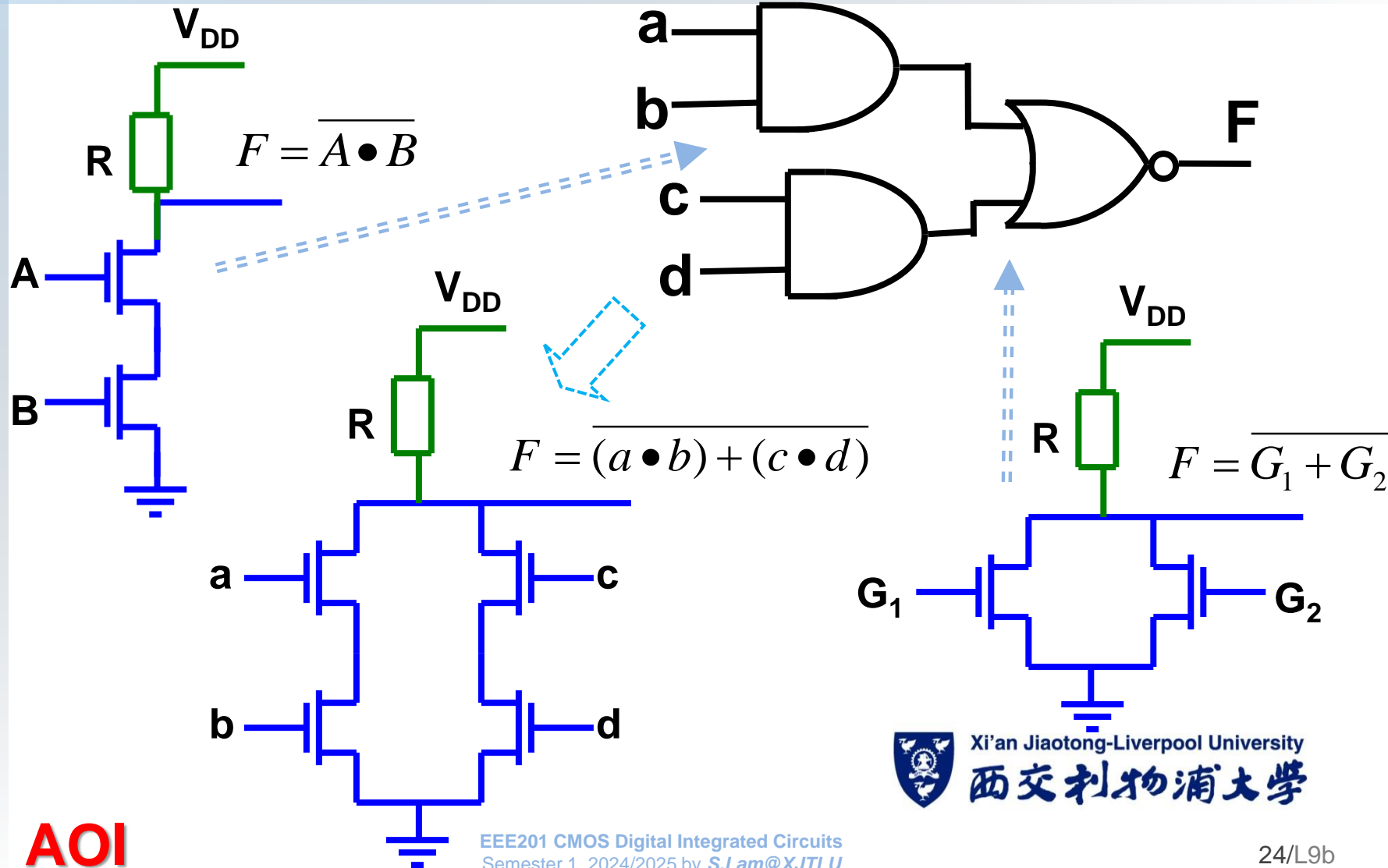
More Complicated Logic Gates

(OR-AND-Inverter)



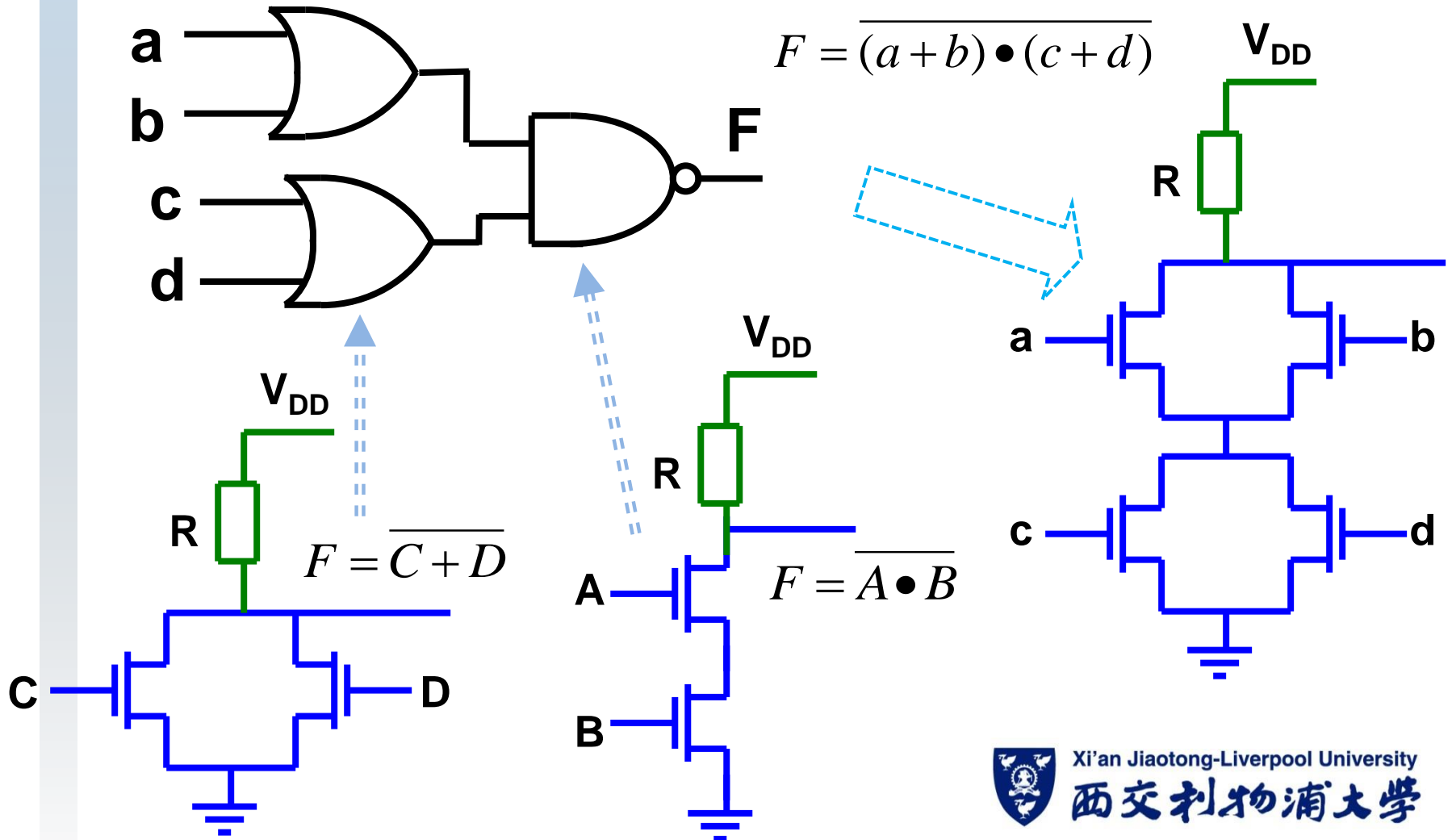
More Complicated Logic Gates

(AND-OR-Inverter)



More Complicated Logic Gates

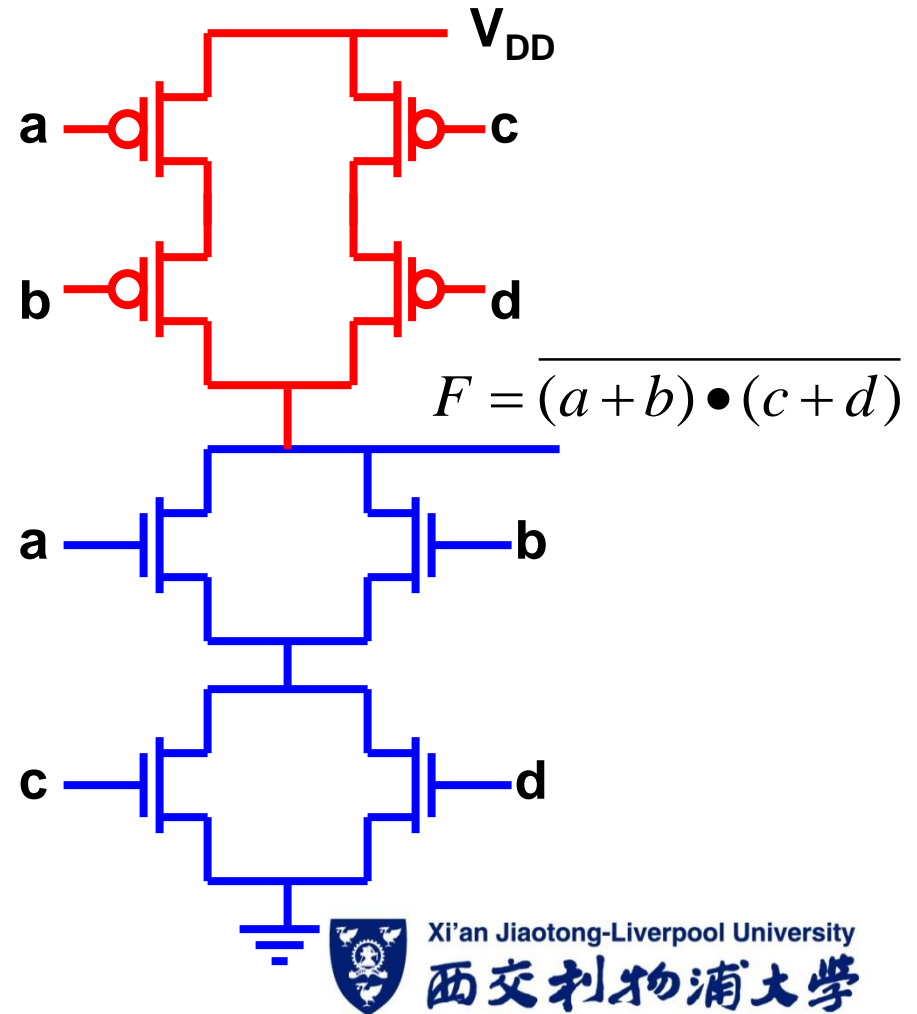
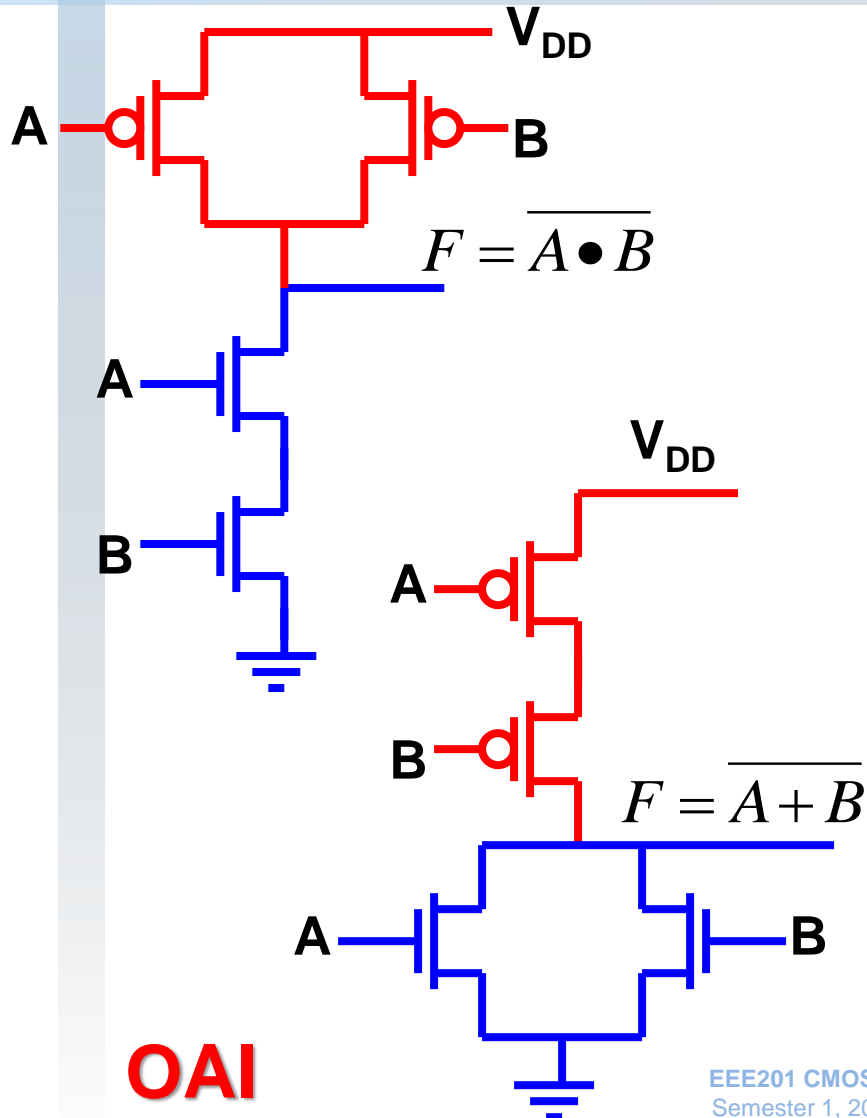
(OR-AND-Inverter)



OAI

More Complicated Logic Gates

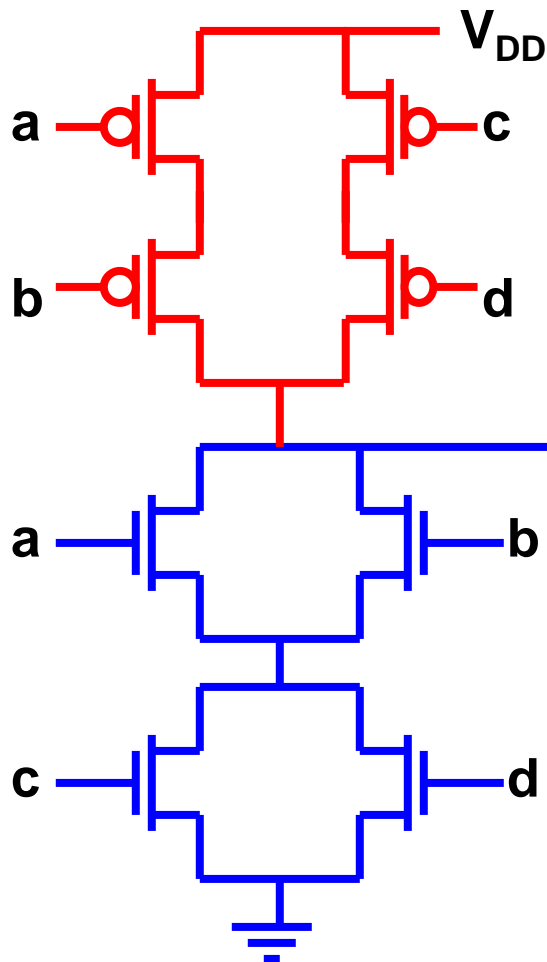
(PMOS network)



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More Complicated Logic Gates

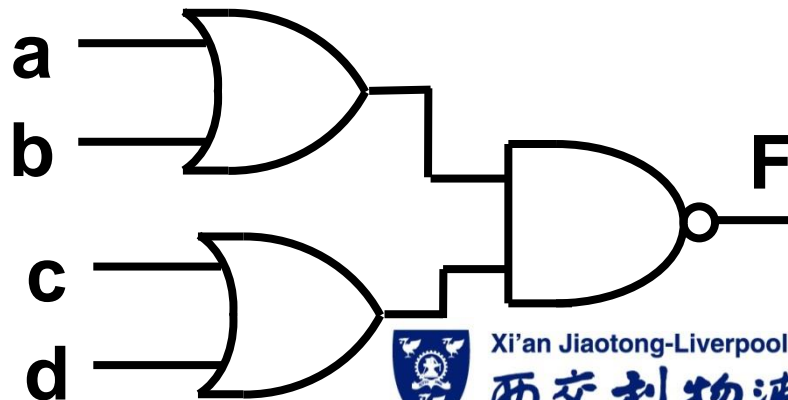
(built from NAND & NOR circuits)



OAI

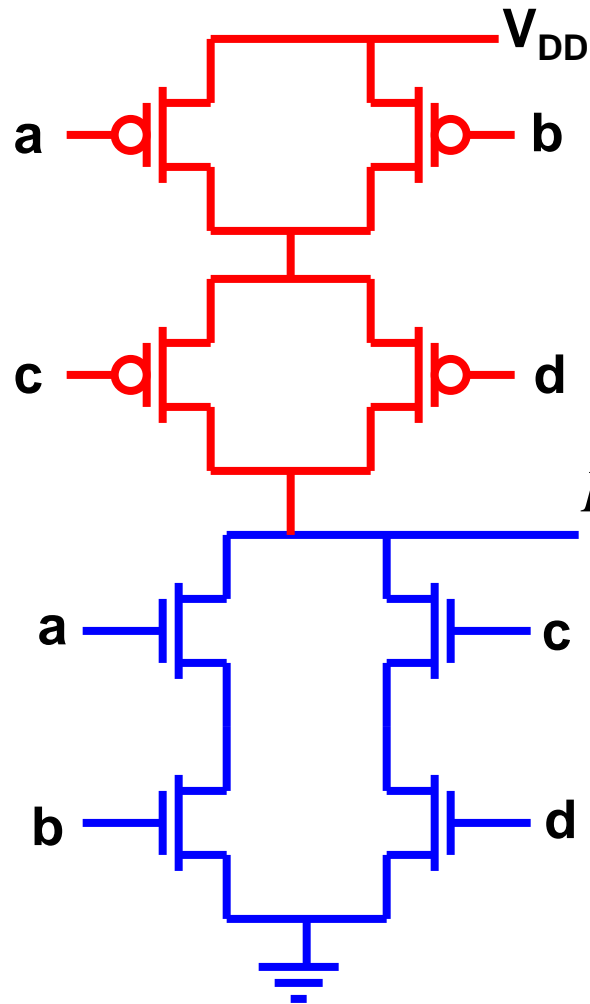
- It can be seen that complicated CMOS logic gates can be built from the NAND and NOR circuits (with either OAI or AOI combinations).

$$F = \overline{(a + b) \bullet (c + d)}$$



More Complicated Logic Gates

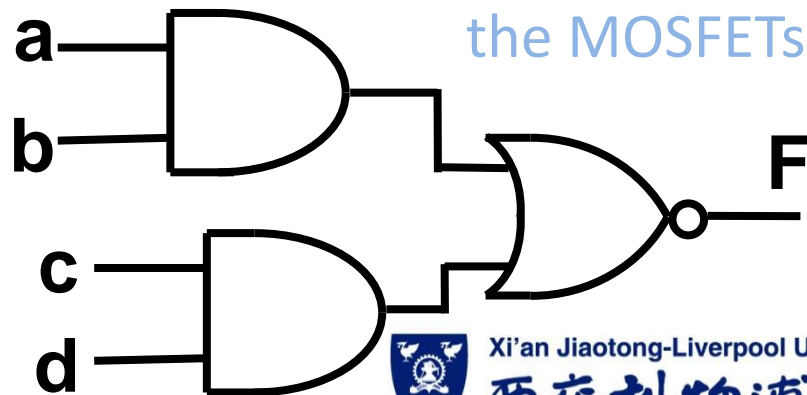
(OAI vs. AOI combinations)



- Note the same MOSFET configuration as in OAI but with the inputs applied differently.

$$F = \overline{(a \bullet b) + (c \bullet d)}$$

➤ Do you see the differences in the inputs applied to the MOSFETs?

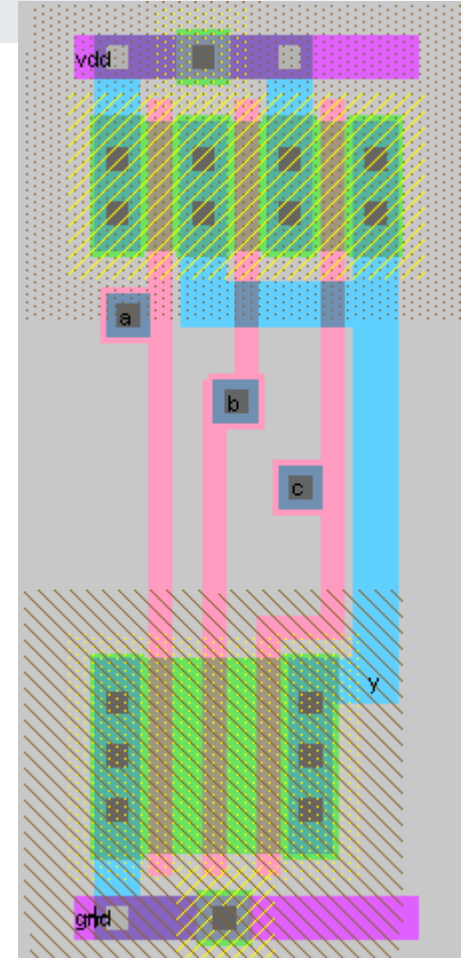
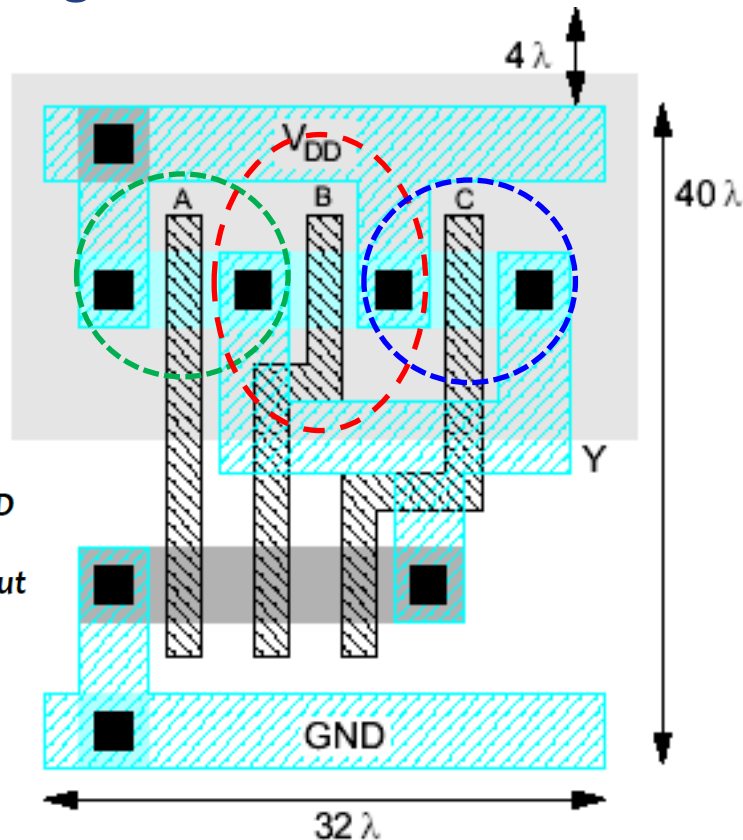
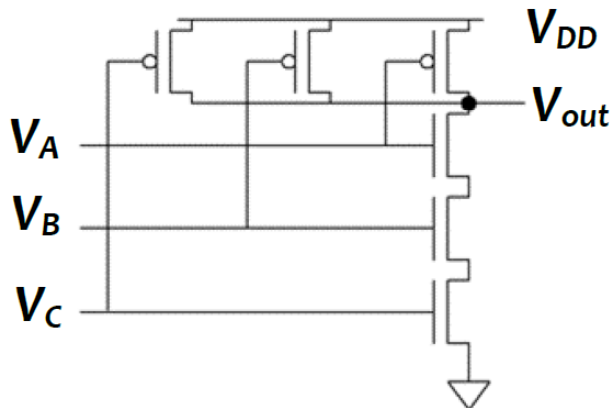


More Complicated Logic Gates

(apply same layout design principles)

- schematic circuit \Rightarrow physical layout
 - 3-input NAND gate in CMOS

design considerations in W_p & W_n , chip area, etc.



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